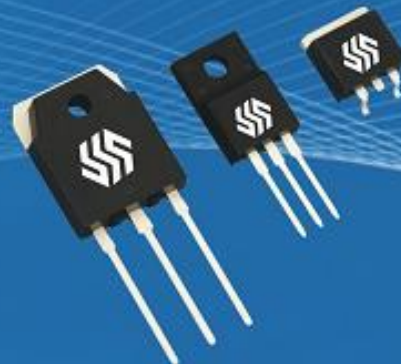




SUPER-SEMI



## SUPER-MOSFET

Super Gate Metal Oxide Semiconductor Field Effect Transistor

100V Super Gate Power Transistor  
SG\*100N08L

Rev. 1.0  
Jul. 2016

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# SGO100N08L

## 100V N-Channel MOSFET

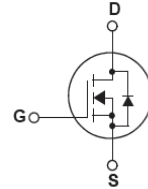
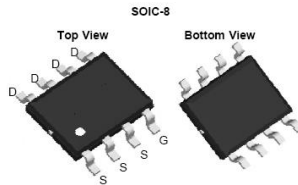
### Description

The SG-MOSFET uses trench MOSFET technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of RDS(ON), Ciss and Coss. This device is ideal for boost converters and synchronous rectifiers for consumer, telecom, industrial power supplies and LED backlighting.

### Features

- VDS 100V
- ID (at Vgs=10V) 14A
- RDS(on) (at Vgs=10V) <8.2mΩ
- (at Vgs=4.5V) <10.5mΩ
- Excellent Avalanche Performance

SGO100N08L



### Absolute Maximum Ratings

Symbol	Parameter	SGO100N08L	Unit
V <sub>DS</sub>	Drain-Source Voltage	100	V
I <sub>D</sub>	Drain Current -Continuous (TA = 25°C) -Continuous (TA = 70°C)	14* 11*	A
I <sub>DM</sub>	Drain Current - Pulsed (Note 1)	56*	A
V <sub>GS</sub>	Gate-Source voltage	±20	V
I <sub>AS</sub>	Avalanche Current, single pulse (Note 1)	38	A
E <sub>AS</sub>	Avalanche Energy, single pulse, L=0.5mH (Note 1)	720	mJ
P <sub>D</sub>	Power Dissipation - TA = 25°C (Note 2) - TA = 70°C	3.1 2.0	W
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range	-55 to +150	°C

\* Drain current limited by maximum junction temperature.

### Thermal Characteristics

Symbol	Parameter	SGO100N08L	Unit
R <sub>θJA</sub>	Maximum Junction-to-Ambient, t<10s(Note 3)	31(typ.)	°C/W
	Maximum Junction-to-Ambient, Steady-State(Note 3,4)	59(typ.)	°C/W
R <sub>θJL</sub>	Maximum Junction-to-Lead, Steady-State	16(typ.)	°C/W



# Electrical Characteristics $T_J = 25^{\circ}\text{C}$ unless otherwise noted

SGO100N08L 100V N-Channel MOSFET

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A, T_J = 25^{\circ}\text{C}$	100	115	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 100V, V_{GS} = 0V$ $-T_J = 55^{\circ}\text{C}$	-	-	1 5	$\mu A$ $\mu A$
$I_{GSSF}$	Gate-Body Leakage Current, Forward	$V_{GS} = 20V, V_{DS} = 0V$	-	-	100	nA
$I_{GSSR}$	Gate-Body Leakage Current, Reverse	$V_{GS} = -20V, V_{DS} = 0V$	-	-	-100	nA
<b>On Characteristics</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.4	2.0	2.3	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10V, I_D = 14A$ $V_{GS} = 4.5V, I_D = 12A$	-	6.8 8.9	8.2 10.5	m $\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = 5V, I_D = 12A$	-	45	-	S
$R_g$	Gate resistance	$V_{GS}=0V, V_{DS}=0V, f=1\text{MHz}$	-	1.4	-	$\Omega$
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS} = 50V, V_{GS} = 0V,$ $f=1\text{MHz}$	-	2570	-	pF
$C_{oss}$	Output Capacitance		-	470	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	16	-	pF
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-On Delay Time	$V_{DS} = 50V, R_G = 3\Omega,$ $I_D = 12A, V_{GS} = 10V$ (Note 5, 6)	-	10	-	ns
$t_r$	Turn-On Rise Time		-	6.5	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	31	-	ns
$t_f$	Turn-Off Fall Time		-	11	-	ns
$Q_g(10V)$	Total Gate Charge	$V_{DS} = 50V, I_D = 12A,$ $V_{GS} = 0\sim 10V$ (Note 5, 6)	-	39	-	nC
$Q_g(4.5V)$	Total Gate Charge		-	19	-	nC
$Q_{gs}$	Gate-Source Charge		-	7	-	nC
$Q_{gd}$	Gate-Drain Charge		-	9.5	-	nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain-Source Diode Forward Current		-	-	4.5	A
$I_{SM}$	Maximum Pulsed Drain-Source Diode Forward Current		-	-	14	A
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0V, I_S = 1A$	-	0.7	1.0	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0V, V_R=50V, I_S = 12A$	-	31	-	ns
$Q_{rr}$	Reverse Recovery Charge	$dI_F/dt = 500A/\mu s$ (Note 5)	-	145	-	nC

## NOTES:

1. Repetitive Rating: Pulse width limited by maximum junction temperature  $T_{J(MAX)}=150^{\circ}\text{C}$ . Ratings are based on low frequency and duty cycles to keep initial  $T_J=25^{\circ}\text{C}$ .
2. The power dissipation PD is based on  $T_{J(MAX)}=150^{\circ}\text{C}$ , using  $\leq 10s$  junction-to-ambient thermal resistance.
3. The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^{\circ}\text{C}$ . The value in any given application depends on the user's specific board design.
4. The  $R_{\theta JA}$  is the sum of the thermal impedance from junction to lead  $R_{\theta JL}$  and lead to ambient.
5. Pulse Test: Pulse width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$
6. Essentially Independent of Operating Temperature Typical Characteristics

# Typical Performance Characteristics

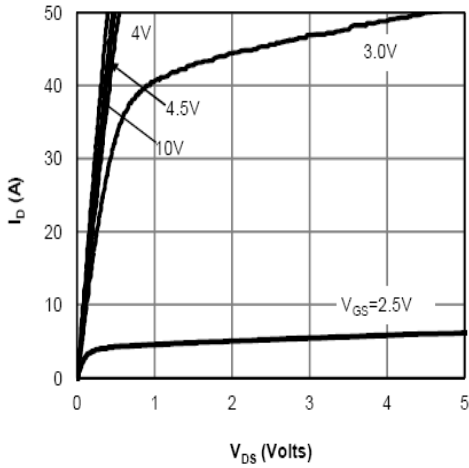


Figure 1: On-Region Characteristics

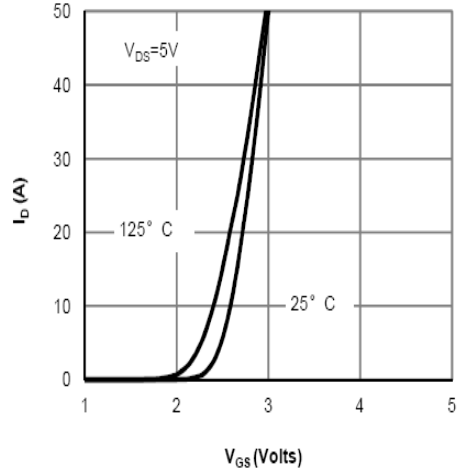


Figure 2: Transfer Characteristics

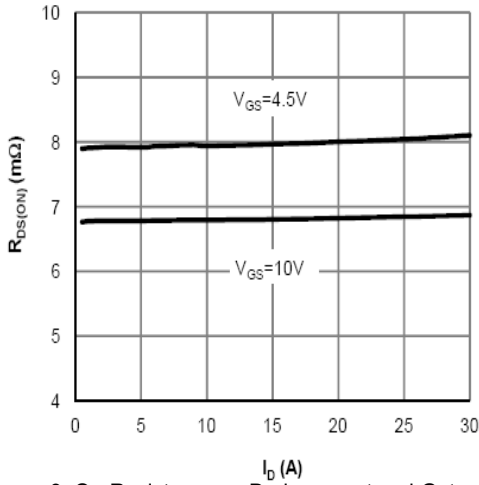


Figure 3: On-Resistance vs Drain current and Gate voltage

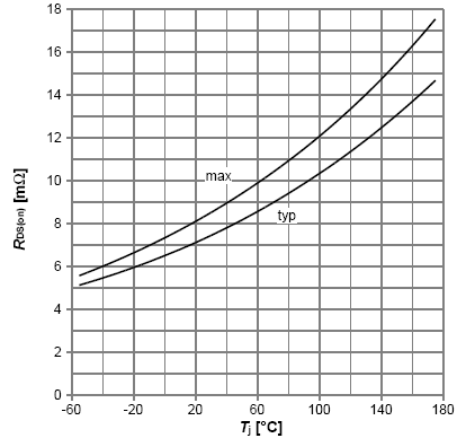


Figure 4: On-Resistance vs Junction Temperature

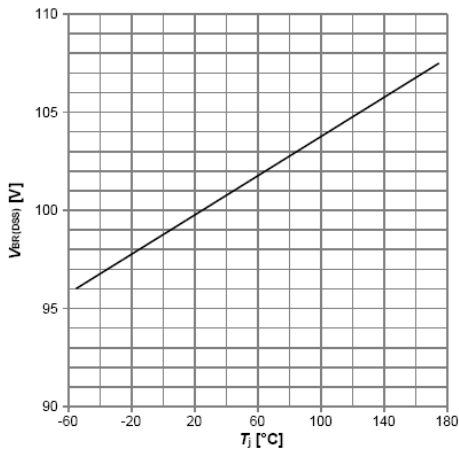


Figure 5: Drain-Source breakdown voltage

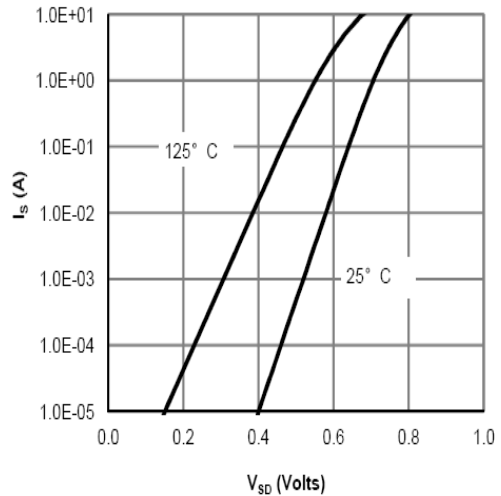


Figure 6: Body-Diode Characteristics

# Typical Performance Characteristics

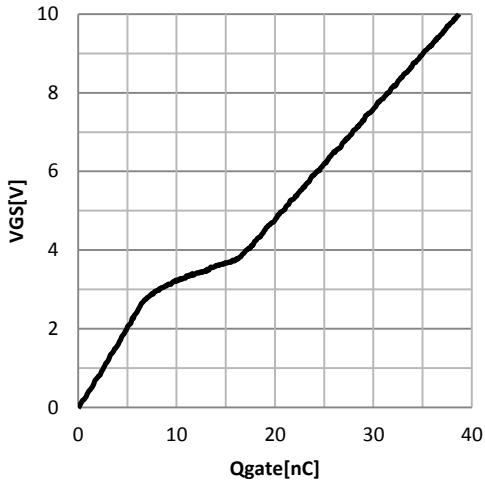


Figure 7: Gate-Charge Characteristics

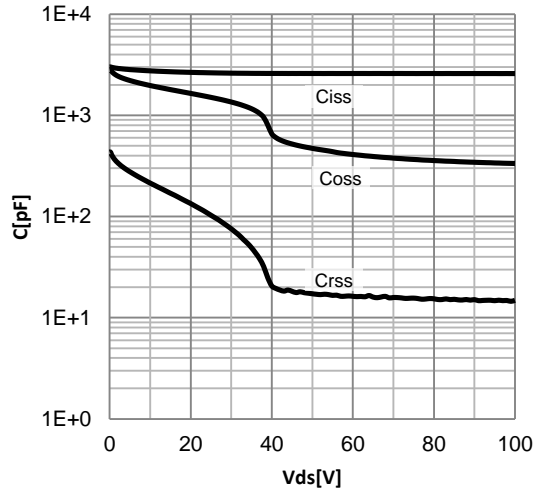


Figure 8: Capacitance Characteristics

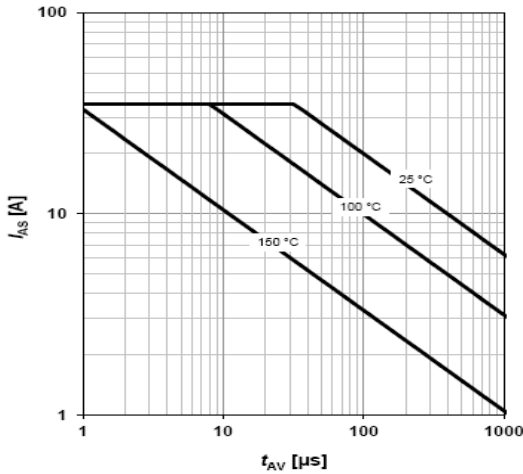


Figure 9: Avalanche Characteristics

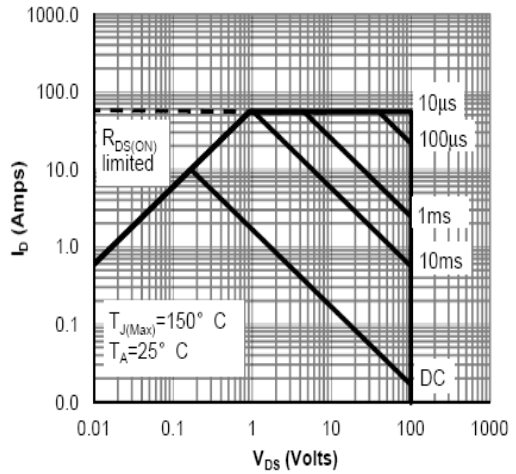


Figure 10: Maximum Forward Biased Safe Operating Area

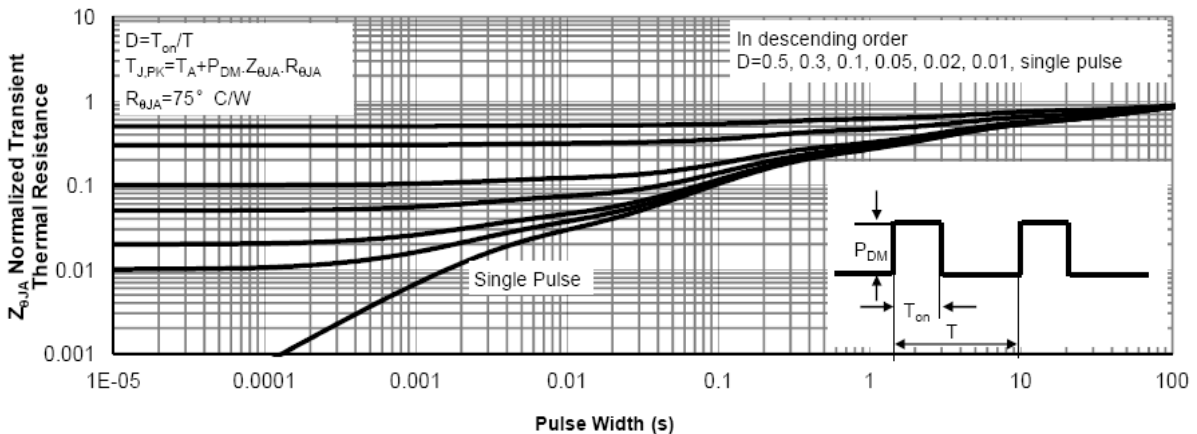
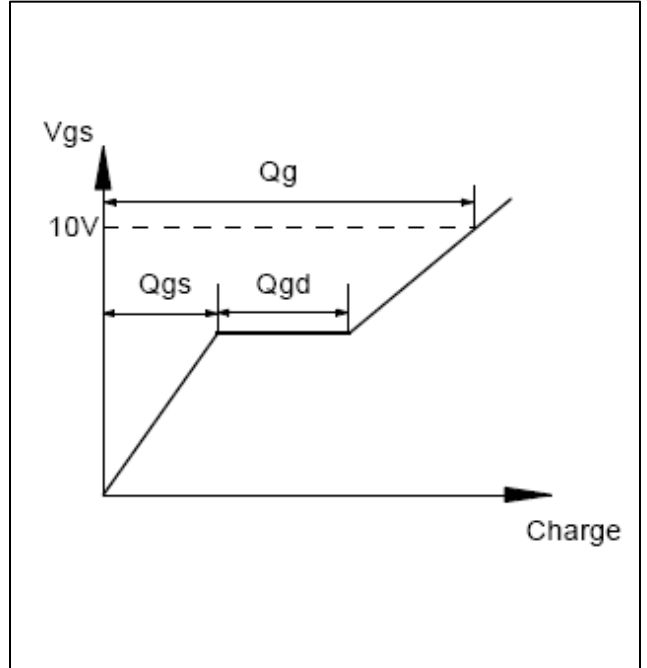
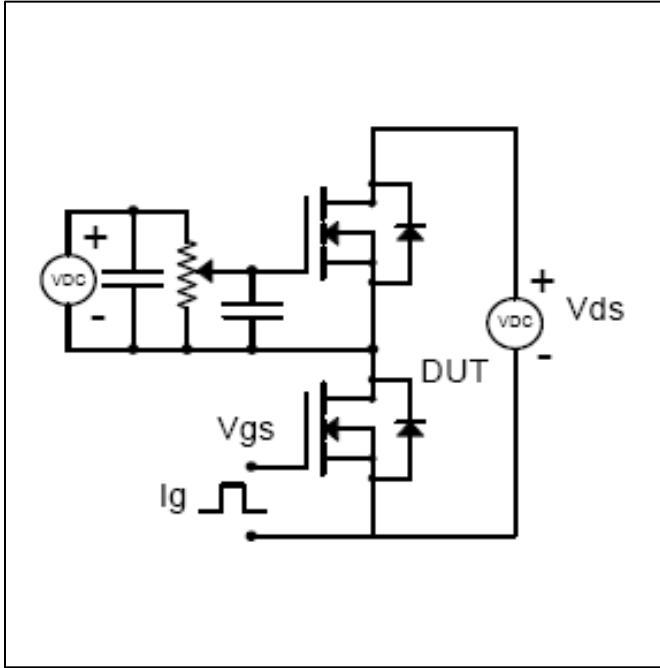
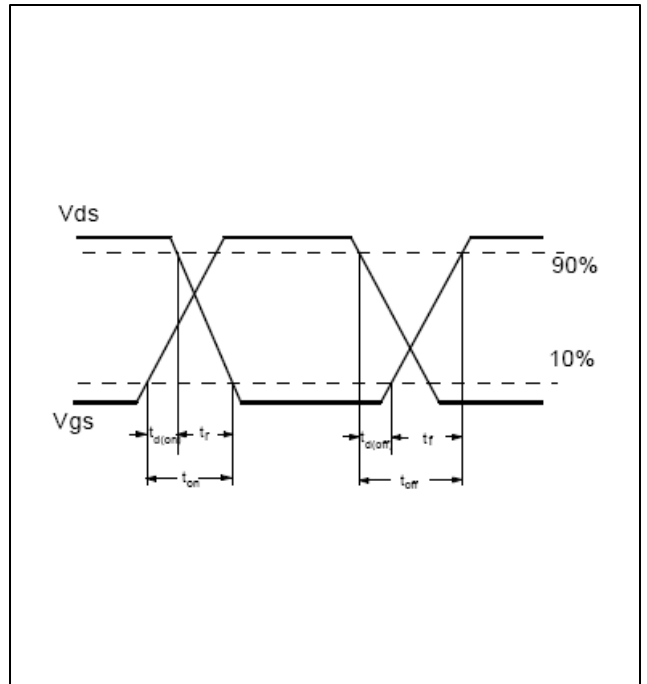
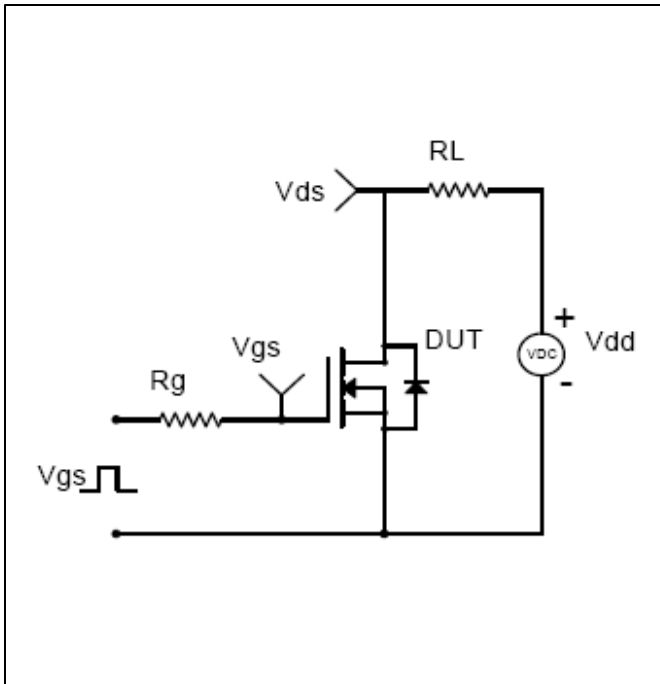


Figure 11: Maximum Transient Thermal Impedance

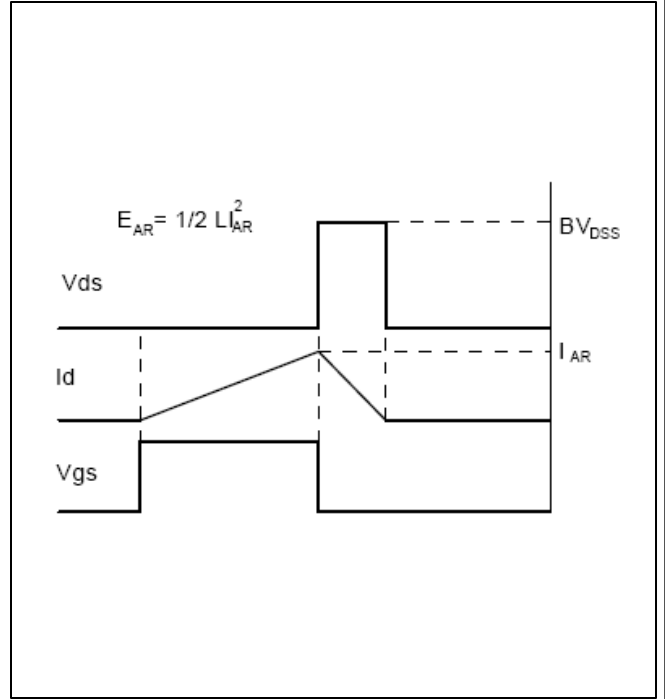
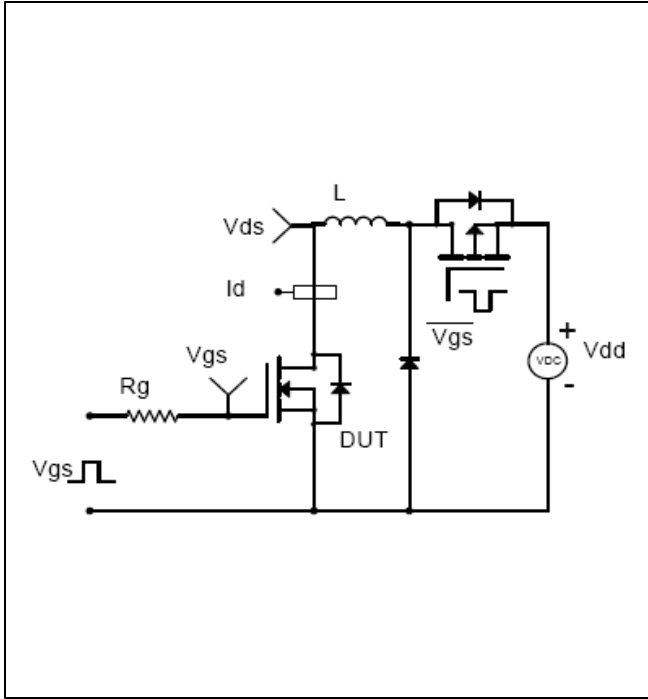
Gate Charge Test Circuit and Waveform



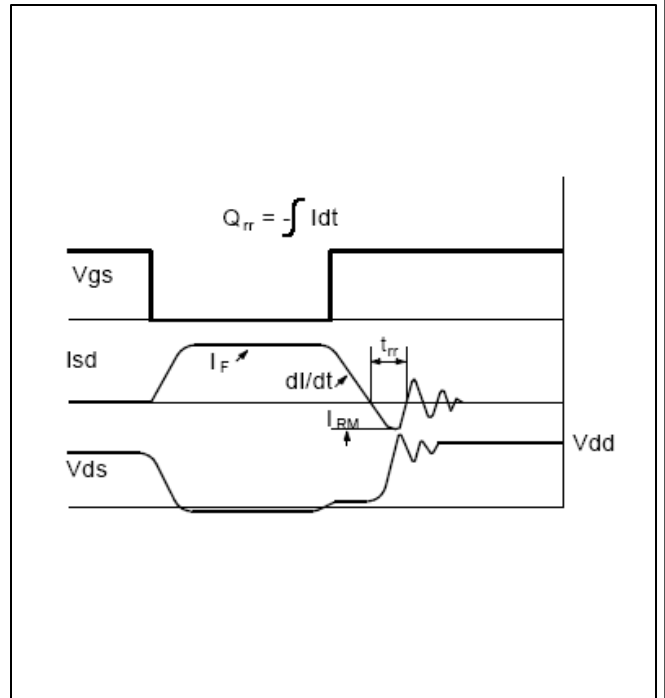
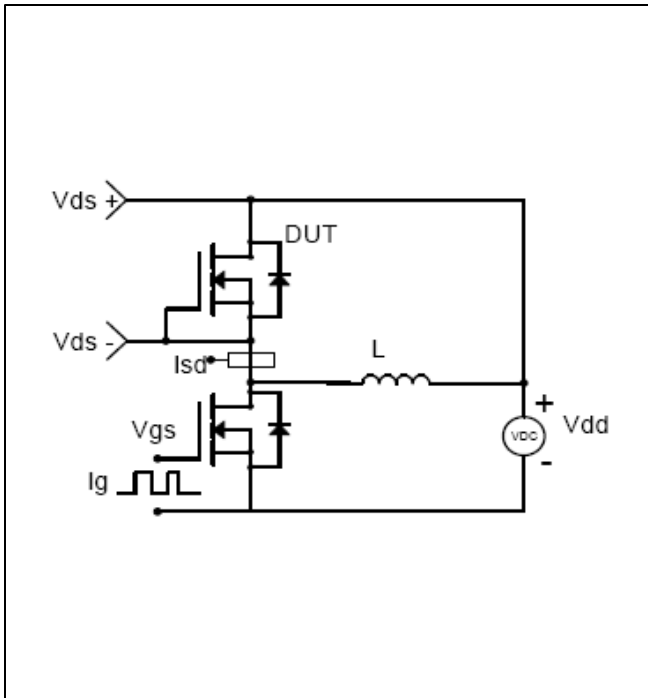
Resistive Switching Test Circuit and Waveforms

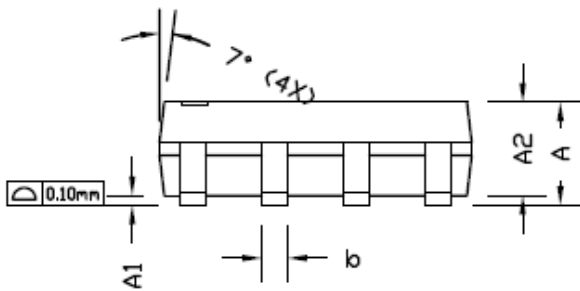
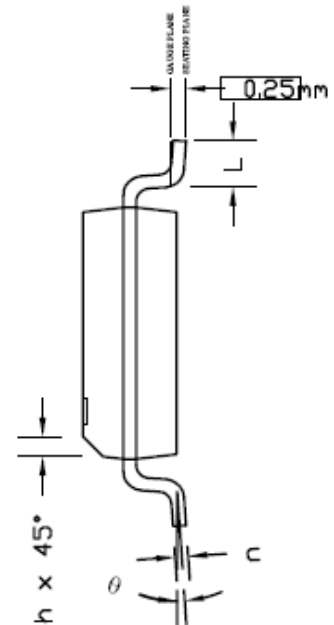
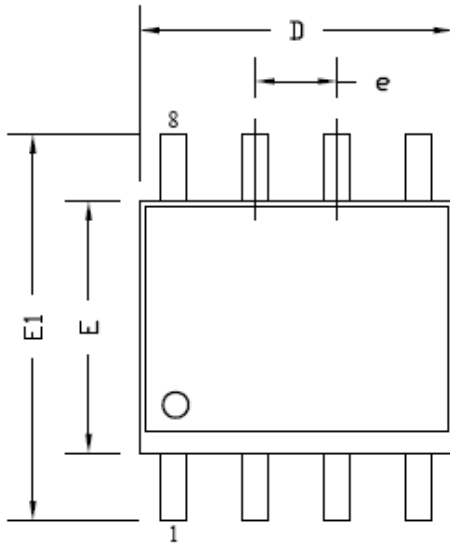


Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

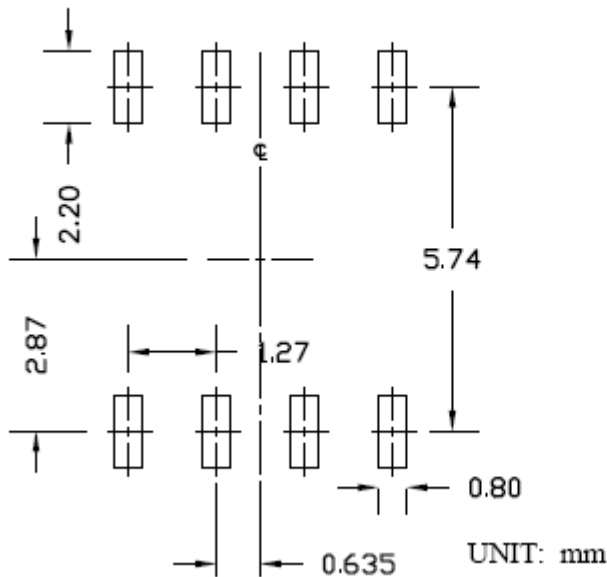


Diode Recovery Test Circuit & Waveforms





**RECOMMENDED LAND PATTERN**



SYMBOLS	DIMENSIONS IN MILLIMETERS		
	MIN	NOM	MAX
A	1.35	1.65	1.75
A1	0.10	0.15	0.25
A2	1.25	1.50	1.65
b	0.31	0.41	0.51
c	0.17	0.20	0.25
D	4.80	4.90	5.00
E	3.80	3.90	4.00
e	1.27 BSC		
E1	5.80	6.00	6.20
h	0.25	0.30	0.50
L	0.40	0.69	1.27
$\theta$	$0^\circ$	$4^\circ$	$8^\circ$



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